Artificial Intelligence on MEMS/Microdevices/Microsystems

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Message from the Guest Editors

Dear Colleagues,

This Special Issue will be focused on micro-electromechanical systems (MEMS)/microdevices and systems with artificial intelligence (AI). Artificial intelligence (AI), through those devices and systems, makes it possible for machines to learn from experience, adjust to new inputs, and perform human-like tasks. Making microstructures is being challenging task day by day. Therefore, in order to improve and optimize device and system performance, AI is a significant candidate that can mitigate the problem occurring in those devices and systems. This Special Issue seeks research papers and review articles that focus on novel methodological developments of AI on MEMs/microdevices and systems for various communication systems.

We look forward to receiving your submissions!

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Special Issue

Editor-in-Chief

Message from the Editor-in-Chief

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